



Docket No. A-67736-1/MSS/TJH  
Dorsey Matter No.: 463035-19

**CERTIFICATE OF MAIL UNDER 37 C.F.R. 1.10**

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Box Fee Amendment, Assistant Commissioner for Patents, Washington, D.C. 20231 on October 2, 2002.

Signed:

*Laura Lee Mosier*  
Laura Lee Mosier

#3/1  
et g TM  
10-15-02  
AW

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of:  
SAVAGE *et al.*

Application No. 09/767,659  
Filed: January 22, 2001

For: Semiconductor Wafer Processing  
System with Vertically-Stacked  
Process Chambers and Single-Axis  
Dual Wafer Transfer System

Examiner: FOX, Charles A.

Art Unit: 3652

Date: October 2, 2002

**AMENDMENT**

Box Fee Amendment  
Assistant Commissioner for Patents  
Washington, D.C. 20231

RECEIVED  
OCT 11 2002  
GROUP 3600

Sir:

This Amendment is responsive to the Office Action mailed April 2, 2002. A petition of three-month extension of time with the appropriate fee is enclosed herewith to obtain time for response to October 2, 2002. Please amend the application as follows:

In the Claims:

Please amend claim 21 to read as shown:

21. (Amended) A method of semiconductor wafer processing according to claim 19, wherein the providing step further includes providing a cooling plate below the transfer arm within said loadlock chamber, said method further comprising:

transferring said processed wafer from said lower wafer shelf to said cooling plate.

**REMARKS**

This amendment is submitted in response to the Office Action dated April 2, 2002. Claim 21 is amended to better recite the features of the invention. Support for this amendment is found in the specification on page 12. Claims 19-24 are pending in this application.

10/09/2002 AOSMAN1 00000150 09767659

01 FC:117

920.00 00